

# PATENT ABSTRACTS OF JAPAN

(11)Publication number : 58-189273

(43)Date of publication of application : 04.11.1983

(51)Int.Cl.

C09J 3/14  
C09J 3/16  
// C08K 5/00  
C08K 5/54  
C08L 21/00  
C08L 23/02  
C08L 25/02  
C08L 31/02  
C08L 33/04  
C08L 67/00

(21)Application number : 57-072035

(71)Applicant : KAO CORP

(22)Date of filing : 28.04.1982

(72)Inventor : OKADA CHI HARU

## (54) COMPOSITION FOR FOAMED HOT-MELT ADHESIVE

(57)Abstract:

PURPOSE: To provide the titled compsn. with stable foamability, showing effective sealing performance when applied to rough surfaces, by incorporating a surface-active fluorine compd. (or an organosilicon compd.) with a thermoplastic resin.

CONSTITUTION: 100pts.wt. thermoplastic resin which melts at 70W250° C and becomes fluid, selected from an addn. polymer [e.g., ethylene (co) polymer, acrylic resin] and an ester-type condensation polymer (e.g, polyester prepared by condensation of an acid component consisting mainly of terephthalic acid and a diol component such as ethylene glycol) is mixed with about 0.001W5pts.wt. surface- active fluorine compd. (e.g., perfluoroalkylethylene oxide adduct) and/or organosilicon compd. (e.g., dimethylpolysiloxane/polyethylene oxide copolymer) under heating and melted to form a compsn. for foamed hot-melt adhesives.

## LEGAL STATUS

[Date of request for examination]

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's decision of rejection]

[Date of extinction of right]